Datasheet

M.2 (S80) 3TE7 series

- SATA III soultion for industrial field
- Exclusive L^3 architecture
- DRAM-less, 100% data integrity
- Excellent random performance
- Supports TRIM/NCQ/SMART
- Built in iData Guard
- Compatible with M.2 2280-D2-B-M standard
- Designed with hardware LDPC ECC engine



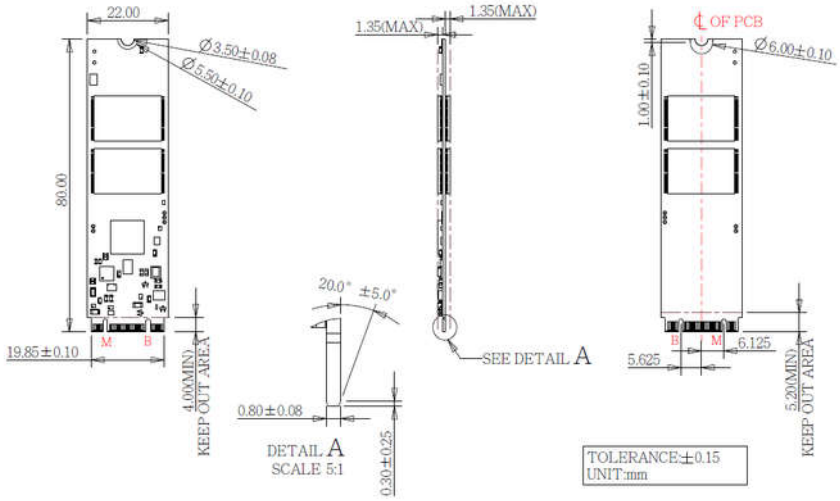
Introduction

Innodisk M.2 (S80) 3TE7 is SATA III 6.0 Gb/s flash based disk, which adopts latest SATA III NAND controller with Innodisk's exclusive L³ FW architecture. The upgraded L³ FW architecture, combining Innodik signature 4K mapping algorithm L² FW architecture with powerful LDPC technology, makes 3TE7 series have outstanding high IOPS, better data integrity and extended lifespan through reducing the bad block number happening. Built-in thermal sensor, and iData Guard ensure data integrity and reliability of 3TE7 for industrial applications.

Innodisk M.2 (S80) 3TE7 is designed for industrial field, and supports several standard features, including TRIM, NCQ, and S.M.A.R.T. In addition, Innodisk's exclusive industrial-oriented firmware provides a flexible customization service, making it perfect for a variety of industrial applications.

M.2 (S80)
3TE7 series

Diagram



Contact us for more information about the M.2 (S80) 3TE7.

Innodisk is a service-driven provider of industrial embedded flash and DRAM storage products and technologies, with a focus on the cloud computing, industrial/embedded, and aerospace and defense industries.

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Specifications

Interface	SATA III
Flash Type	3D TLC
P/E cycle	3,000
Capacity	32GB~2TB
Max. Channels	4
Sequential R/W (MB/sec, max.)	550/520
Max. Power Consumption	2.3W(3.3V x696mA)
Thermal Sensor	√
External DRAM buffer	-
H/W Write Protect	Optional
ATA Security	√
S.M.A.R.T.	√
Dimension (WxLxH)	22.0 X 80.0 X 3.5 mm (Max)
Environment	Vibration: 20G @7~2000Hz Shock: 1500G @ 0.5ms Storage Temperature: -40°C ~ +85°C MTBF: 3 million hours

Ordering Information

Operation Temp.	32GB	64GB	128GB	256GB	512GB	1TB	2TB
Standard Grade (0°C ~ +70°C)	DEM28-32GDK1EC1SF	DEM28-64GDK1EC*DF	DEM28-A28DK1%C*QF	DEM28-B56DK1%C*QF	DEM28-C12DK1%C*QF	DEM28-01TDK1%CAQF	DEM28-02TDK1%CAQF
Industrial Grade (-40°C ~ +85°C)	DEM28-32GDK1EW1SF	DEM28-64GDK1EW*DF	DEM28-A28DK1EW*QF	DEM28-B56DK1EW*QF	DEM28-C12DK1EW*QF	DEM28-01TDK1EWAQF	X

%.E: 64 layers 3D TLC; G: 96 layers 3D TLC; K: 112 layers 3DTLC

*. PCB version control